

Dkt. 2271/66770

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:

Hideyuki YAMAGUCHI

Serial No.

10/075,481

Group Art Unit: 1734

Date Filed

February 13, 2002

Examiner: Not yet known

For

HEAT-SENSITIVE STENCIL SHEET AND METHOD OF MAKING

THE SAME

Cooper & Dunham LLP 1185 Avenue of the Americas New York, N.Y. 10036 (212) 278-0400 November 17, 2003

Commissioner for Patents P.O. Box 1450 Alexandria, V.A. 22313-1450

INFORMATION DISCLOSURE STATEMENT

In order to ensure compliance with the applicant's duty of disclosure under 37 C.F.R. §1.56 and §1.97(a)-(d), Applicant hereby submits this Information Disclosure Statement as a supplement to the Information Disclosure Statement filed on June 25, 2002 and the Information Disclosure Statement filed on November 21, 2002, in connection with the above-identified application.

It is respectfully requested that the information cited in annexed Form PTO-1449 be considered by the Examiner in connection with the above-identified patent application, and that

I hereby certify that this paper is being deposited this date with the U.S. Postal Service as first class mail addressed to the Commissioner for Patents, P.Q. Box 1450, Alexandria, VA 22313-1450.

Paul Teng Reg. No. 40,837 Jorember 17,200

Date

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Hideyuki YAMAGUCHI, S.N. 10/075,481 Page 2

such art be made of record in said application.

The citation of the listed items is not a representation that they constitute a complete or exhaustive listing of the relevant art or that these items are prior art. The items listed are submitted in good faith, but are not intended to substitute for the Examiner's search. It is hoped, however, that in addition to apprising the Examiner of the particular items, they will assist in identifying fields of search and in making as full and complete a search as possible.

The items listed were cited in a search report (copy enclosed) in connection with a European application corresponding to the present U.S. application.

The filing of this Information Disclosure Statement is not an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. §1.56(b).

To the best of Applicant's knowledge, this Information Disclosure Statement is being filed before the date of mailing of a first Office Action on the merits in connection with this case.

The Office is hereby authorized to charge any additional fees which may be required for consideration of this Information Disclosure Statement to our Deposit Account No. 03-3125.

Early and favorable consideration of the case is respectfully requested.

Respectfully submitted,

Paul Teng, Reg. No. 40,837

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U.S. Department of Commerce Patent and Trademark Office

Atty. Docket No. 2271/66770

Serial No. 10/075,481

Applicant

Hideyuki YAMAGUCHI

Filing Date February 13, 2002

Group 1734

INFORMATION DISCLOSURE CITATION BY APPLICANT (Use several sheets if necessary)

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EXAMINER

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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.